Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2013-05-17
Contact Name *	Refer to " Supplier Comment" section	Contact Title	Refer to " Supplier Comment" section
Contact Phone *	Refer to " Supplier Comment" section	Contact Email *	Refer to " Supplier Comment" section
Authorized Representative *	Giovanni Giacopello	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to " Supplier Comment" section	Representative Email *	Refer to " Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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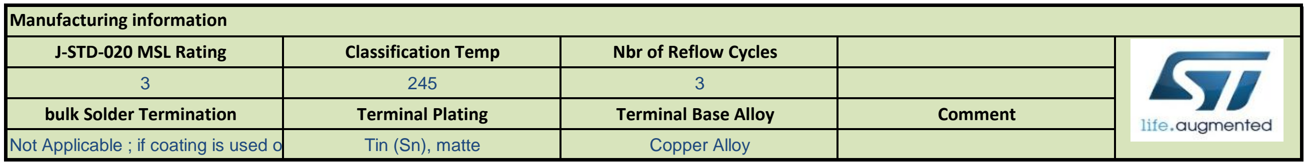
Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.		

Product				
Mfr Item Number	**Mfr Item Name**	**Version**	**Mfr Site**	**Date**
M41T94MH6F	HZMH*B6AA94H	A	MU1A	2013-05-17
	Amount	**UoM**	**Unit type**	**ST ECOPACK Grade**
	947.50	mg	Each	ECOPACK® 1



Manufacturing information				
J-STD-020 MSL Rating	**Classification Temp**	**Nbr of Reflow Cycles**		
3	245	3		
bulk Solder Termination	**Terminal Plating**	**Terminal Base Alloy**	**Comment**	
Not Applicable ; if coating is used o	Tin (Sn), matte	Copper Alloy		

Package Designator	**Size**	**Nbr of instances**	**Shape**	
SOF	17.7 - 8.2 - 3	28	gull wing	
Comment				

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	**Response**
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	**true**
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false

Exemption Id.	**Description**
6c	Copper alloy containing up to 4 % lead by weight

QueryList :REACH-18 June 2012				
Query				**Response**
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				**true**
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HZMH*B6AA94H					
Homogeneous Material	**Material Group**	**Mass**	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Silicon Die	Other inorganic materials	8.382	mg	supplier	Silicon die	Silicon	7440-21-3		8.378	mg	999523	8842
Silicon Die				supplier	die metallization	Aluminium(Al)	7429-90-5		0.001	mg	119	1
Silicon Die				supplier	die metallization	Copper (Cu)	7440-50-8		0.002	mg	239	2
Silicon Die				supplier	die metallization	Titanium (Ti)	7440-32-6		0.001	mg	119	1
Lead-frame	Copper & its alloys	283.207	mg	supplier	alloy	Copper (Cu)	7440-50-8		273.716	mg	966487	288882
Lead-frame				supplier	alloy	Iron (Fe)	7439-89-6		6.589	mg	23266	6954
Lead-frame				supplier	alloy	Zinc (Zn)	7440-66-6		0.337	mg	1190	356
Lead-frame				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.236	mg	833	249
Lead-frame				supplier	metallization	Silver (Ag)	7440-22-4		2.329	mg	8224	2458
Die Attach	Other inorganic materials	1.081	mg	supplier	glue	Silver (Ag)	7440-22-4		0.811	mg	750231	856
Die Attach				supplier	glue	Epoxy Cresol Novolak	29690-82-2		0.268	mg	247919	283
Die Attach				supplier	glue	1-isopropyl-2,2-dimethyltrimethylene diisobut	6846-50-0		0.002	mg	1850	2
Bonding wire		0.818	mg	supplier	wire	Gold (Au)	7440-57-5		0.818	mg	1000000	863
Encapsulation	Other inorganic materials	562.038	mg	supplier	Moulding Compound	Silica, vitreous	60676-86-0		449.63	mg	799999	474544
Encapsulation				supplier	Moulding Compound	Epoxy Cresol Novolak	29690-82-2		39.343	mg	70001	41523
Encapsulation				supplier	Moulding Compound	Phenol resin	9003-35-4		22.482	mg	40001	23728
Encapsulation				supplier	Moulding Compound	Biphenyl epoxy resin	85954-11-6		33.722	mg	60000	35591
Encapsulation				supplier	Moulding Compound	Antimony Trioxide	1309-64-4		6.744	mg	11999	7118
Encapsulation				supplier	Moulding Compound	Brominated Epoxy Resin	40039-93-8		8.431	mg	15001	8898
Encapsulation				supplier	Moulding Compound	Carbon Black	1333-86-4		1.686	mg	3000	1779
Finishing	Solder	7.695	mg	supplier	connection coating	Tin (Sn)	7440-31-5		7.695	mg	1000000	8121
Socket	Other inorganic materials	84.279	mg	supplier	Pin/Shell	Copper (Cu)	7440-50-8		42.291	mg	501798	44634
Socket				supplier	Pin/Shell	Zinc (Zn)	7440-66-6		24.343	mg	288838	25692
Socket				supplier	R	Lead	7439-92-1	6c. Lead as an alloy	2.131	mg	25285	2249
Socket				supplier	Contact	Copper (Cu)	7440-50-8		14.037	mg	166554	14815
Socket				supplier	Contact	Beryllium	7440-41-7		0.257	mg	3049	271
Socket				supplier	Contact Top Plate	Gold (Au)	7440-57-5		0.567	mg	6728	598
Socket				supplier	Contact underplate	Nickel	7440-02-0		0.653	mg	7748	689